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「封装、挠性板、刚挠性板的先进技术」研讨会

2006年10月24日 深圳・深航锦江国际酒店　2006年10月26日 苏州・凯莱大酒店

2006

Taibei: October 16-17
Shenzhen: October 24
Suzhou: October 26

研讨会专家及讲员资料 一

Takuya Yamamoto

Takuya Yamamoto 是 Oak Mitsui Technoloies 公司的技术市场经理。

Takuya joined Mitsui Mining & Smelting co.,ltd in 1995 as a research engineer at technical department of copper foil division. Has been involved in developing copper foil for advanced printed circuit boards. From Dec.2002 to Sep. 2005, engaged in embedded capacitor marketing as a Technical marketing manager at Oak Mitsui Technologies. Currently, taking position of marketing newly developed copper foil, DFF® for COF and Flex applications. Received Master of engineering, Metallurgy, from Graduate school of Engineering, Kyoto University, Japan, March 1995.

James J. Hickman. PhD.

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James J.Hickman.phD 是 Hickman 协会研究人员。

Dr. Hickman has been associated with the chemical and electronic industries for over 30 years primarily with DuPont where he has held avariety of international and domestic senior management positions. His primary interests have been in printed circuit fabrication and assembly, semiconductor materials, IC packaging and HDI materials and associated leading edge technologies. He has held a variety of positions: research chemist, product management, sales, marketing, operations, R&D, strategic positioning including acquisitions and JV's and senior management.

He has been instrumental in the creation, development and growth of many new businesses and has been a leader in the value positioning of these businesses on a global basis. Since retiring from DuPont at the end of 1998, he has been consulting in the electronics industry. Most recently, he has been working with DKN Research on flexible PWBs, SBA Materials Inc on ordered mesoporous low-k and high-k materials for the next generation IC wafer fabrications and private market studies for his clients. Jim has been active in the IPC for over 25 years and has been a recipient of the "IPC President's Award" and other Awards. He was a founding member of the Supplier's Management Council Steering Committee and chairs the subcommittee on strengthening the technology exchanges between suppliers and OEM's.

He is also a member of the IPC Government Trade Committee, a past member of the TMRC Steering Committee and many other IPC committees. Jim has been active with CircuiTree and The Board Authority. He has also been an advisor to North Carolina State University, NCMC and SRC in microelectronics. Jim holds a BS in Chemistry from Tufts University and a Ph.D. in physical organic chemistry from the University of Notre Dame.

Happy Holden

Asian Pacific Materials　　E-mail: 1HH@asianpm.com

Happy Holden 是 Asian Pacific Materials 公司的技术专家。

Happy Holden is currently a PCB Technologist for Asian Pacific materials System Design Division. Mr. Holden has spent 36 years in printed circuit engineering, customer support and development, five of those years in Taiwan and Hong Kong. Mr. Holden was responsible for the creation and startup of the NanYa PCB Division in 1984 while at Hewlett-Packard. Happy retired from H-P in 1996 after 26 years.

A 1968 graduate of OSU in Chemical Engineering, Mr. Holden came to Hewlett-Packard in 1970 after a M.S. degree in Computer Science and a tour of duty in the U.S. Army. He is a member of SMTA, IMAPS, IEEE and the IPC.

研讨会专家及讲员资料 二

Crystal Vanderpan

Underwriters Laboratories Inc. Email: crystal.e.vanderpan@us.ul.com www.ul.com

Crystal Vanderpan 是 UL 实验室的工程师。

Crystal Vanderpan is the Principal Engineer of Printed Circuit Technologies at Underwriters Laboratories Inc. (UL), an independent, not-for-profit, product-safety testing and certification organization. Crystal received a B.S. in Chemical Engineering and Materials Science from UCDavis.

Dennis K. W. Yee

Rohm and Haas Email: SMoroney@rohmhaas.com

Dennis K.W.Yee 是罗门哈斯电子材料亚洲有限公司，亚洲区研究、发展和工程部门经理。

The speaker is the Research, Development and Engineering Manager of Rohm and Haas Electronic Materials – Circuit Board Technology in Asia Region. He has worked in Rohm and Haas for over 12 years since the legacy LeaRonal Asia Limited and has totally over 15 years of field experience on chemical process engineering of PCB manufacturing.

In the recent years, his major focuses are on technical marketing and product development of metallization processes. Dennis received his Bachelor Degree of Science on Applied Chemistry from Hong Kong Baptist University.

John Andresakis

Oak Mitsui Technologies, LLC E-mail: John.Andresakis@oakmitsui.com

John Andresakis 是 Oak-Mitsui 技术公司战略技术部副主任。

John Andresakis- Vice President of Strategic Technology for Oak-Mitsui Technologies has over 26 years experience in the manufacturing of Printed Circuit Boards. Before Oak-Mitsui, he was Engineering Manager for Hadco Corporation (now part of Sanmina-SCI Corporation) at both their Owego, NY and Hudson, NH facilities. In addition to Hadco, John was in Technical Management at Nelco, Digital Equipment and IBM.

He holds a Masters Degree in Chemical Engineering from the University of Connecticut and a Bachelors of Engineering Degree from Cooper Union. He has received 8 patents related to PCB Production and is a member of the IPC Suppliers Technology Council and the various IPC committees developing specifications for Embedded Passives.